IPC ASSOCIATION ELECTRONIE	© Copyright 20	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		nder both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				iterials and	ials and Mfg Information				
upplie	r Information														
Company name* Company unique ID				nique ID	Unique		Inique ID Auth	nique ID Authority				Response Date*			
nsemi											2024-	2024-05-01			
Contact N	Name		Title - Conta	Title - Contact			Phone - Contact*				Email	Email - Contact*			
Product-	Env-Stewards		Product Env	Product Enviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*		Title - Representative			F	Phone - Representative*				Email	Email - Representative*			
Product-	Env-Stewards		Product Enviro Compliance]	NA				Prod	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date		,	Weight*	UOM	Unit Type			
		NTMD6N03R2G NFET SO8 30V 6A		А 32МОНМ		2024-05-01		PH1			71.99	mg	Each		
Ianufa	ncturing Process Infor			.,,	GED 000 MG		D 15	D 1 7	n		1.77		op g	,	
	8		,		-STD-020 MSL	Rating		ess Body T	ss Body Temperature Max Time at Peak					eles	
	Matte Tin (Sn) - annealed		CU Alloy	1			260		C	30	sec	onds 3			
omments				•											
	naximum time at peak temp														
or more	information regarding mate	erial composition	please refer t	o page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.33	mg	Supplier	Silicon (Si)	7440-21-3		1.33	mg
Die Attach	2.4	mg	Supplier	Silver (Ag)	7440-22-4		1.8	mg
			Supplier	Epoxy resins	129915-35-1		0.6	mg
Lead Frame	37.61	mg	Supplier	Silver (Ag)	7440-22-4		0.7898	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0752	mg
			Supplier	Iron (Fe)	7439-89-6		0.9403	mg
			Supplier	Copper (Cu)	7440-50-8		35.8047	mg
Mold Compound-Black	28.58	mg		Epoxy Phenol Resin	proprietary data		3.0009	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.5791	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Cu	0.18	mg	Supplier	Copper (Cu)	7440-50-8		0.18	mg